

| 特征/Features | 外形尺寸/Outline Dimensions | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
|--|--|---------|--|----|---------|---------|---|------|------|---|------|------|---|------|------|---|------|------|---|-----|-----|---|------|------|---|-----|-----|---|-----|-----|---|-----|-----|---|------|------|---|------|------|
| <ul style="list-style-type: none"> ◆ GPP芯片 Glass passivated chip ◆ 低反向漏电流 Low Reverse Leakage Current ◆ 高耐浪涌电流能力 High surge current capability ◆ 接线端与壳体间绝缘耐压2500V Case to Terminal Isolation Voltage 2500V | Case: GBL Series Dimensions in millimeters | | <table border="1"> <thead> <tr> <th>序号</th> <th>Min(mm)</th> <th>MAX(mm)</th> </tr> </thead> <tbody> <tr><td>A</td><td>19.7</td><td>20.3</td></tr> <tr><td>B</td><td>17.2</td><td>17.7</td></tr> <tr><td>C</td><td>10.7</td><td>11.2</td></tr> <tr><td>D</td><td>13.7</td><td>14.2</td></tr> <tr><td>E</td><td>4.8</td><td>5.2</td></tr> <tr><td>F</td><td>0.95</td><td>1.05</td></tr> <tr><td>G</td><td>2.3</td><td>2.7</td></tr> <tr><td>H</td><td>3.3</td><td>3.8</td></tr> <tr><td>I</td><td>3.3</td><td>3.7</td></tr> <tr><td>J</td><td>0.95</td><td>1.05</td></tr> <tr><td>K</td><td>0.45</td><td>0.55</td></tr> </tbody> </table> | 序号 | Min(mm) | MAX(mm) | A | 19.7 | 20.3 | B | 17.2 | 17.7 | C | 10.7 | 11.2 | D | 13.7 | 14.2 | E | 4.8 | 5.2 | F | 0.95 | 1.05 | G | 2.3 | 2.7 | H | 3.3 | 3.8 | I | 3.3 | 3.7 | J | 0.95 | 1.05 | K | 0.45 | 0.55 |
| 序号 | Min(mm) | MAX(mm) | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| A | 19.7 | 20.3 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| B | 17.2 | 17.7 | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
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| 机械参数/Mechanical Data <ul style="list-style-type: none"> ◆ 本体: 塑封 Case: plastic package ◆ 标识/极性: 本体标记 Marking / Polarity: Marked on Body ◆ 重量: 约克 Weight: About 2.2grams | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |

极限值/Maximum Ratings and Thermal Characteristics @ Ta = 25°C unless otherwise noted

| 符号 Symbol | 特性 Characteristic | GBL8 | | | | | | | 单位 Unit |
|-----------------------------------|---|------------|-----|-----|-----|-----|-----|------|------------------|
| | | 005 | 01 | 02 | 04 | 06 | 08 | 10 | |
| V _{RRM} | 最大反向重复峰值电压 Maximum Recurrent Peak Reverse Voltage | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| I _{F(AV)} | 平均整流输出电流 Average Forward Output Rectified Current@Ta=120°C | 8 | | | | | | | A |
| V _F | 正向峰值电压 Forward Voltage Per Leg @I _{FM} =8.0A | 1.05 | | | | | | | V |
| I _{FSM} | 正向浪涌电流 Peak Forward Surge Current 8.3ms Single Half Sine-wave superimposed on rated load | 180 | | | | | | | A |
| I _R | 反向漏电流 Maximum DC reverse current at rated DC blocking voltage per leg | Ta = 25°C | | | 5 | | | | uA |
| | | Ta = 125°C | | | 500 | | | | |
| i ² t | 热容值 Rating for fusing (t<8.3ms) | 134 | | | | | | | A ² S |
| V _{isol} | 绝缘耐压 Rms isolation voltage from case to leads | 2500 | | | | | | | V |
| C _J | 典型结电容 Typical Junction Capacitance | 50 | | | | | | | pF |
| R _{θJC} | 热阻 Maximum thermal resistance per leg | 2 | | | | | | | °C/W |
| T _j , T _{STG} | 结温, 存储条件 Operating Junction and storage temperature range | -55~150 | | | | | | | °C |

Note:
 (1) Junction to case with heatsink
 (2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with M3 screw .

◆ 特性曲线 (典型) Characteristics(Typical)

Fig 1-forwardCurrent derating Curve
图1正向电流降额曲线

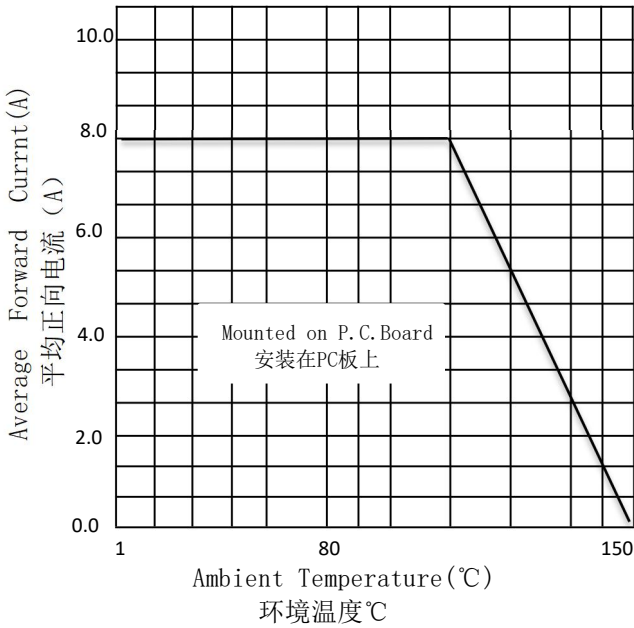


Fig.2-Maximum Non-Repetitive Surge Current
图2 最大不重复正向浪涌曲线

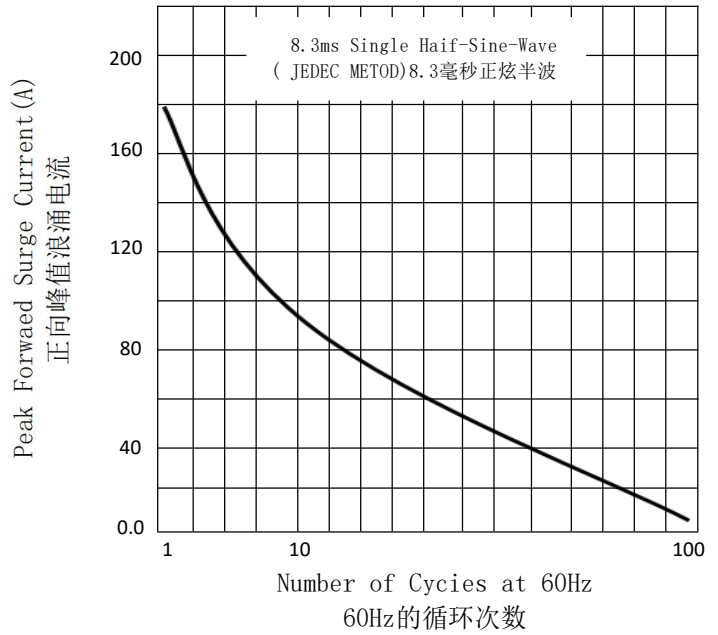


Fig.3-Typical Reverse Characteristics
图3. 典型的反向特性

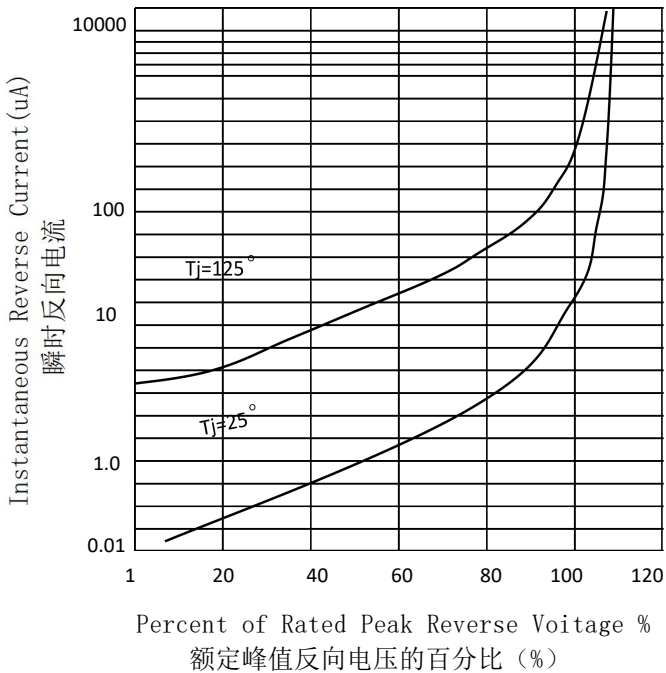


Fig.4-Typical Forward Characteristics
图4. 典型的正向特性

